

Amendments to Claims:

Claim 1 (previously presented): An improved process for bonding difficult-to-bond substrates comprising bonding a first substrate to a second substrate with a thermoplastic hot melt adhesive composition, said composition comprising an ethylene n-butyl acrylate copolymer and a modified terpene tackifier.

Claim 2 (original): The process of claim 1 wherein the modified terpene is a terpene phenolic.

Claim 3 (original): The process of claim 1 further comprising a wax.

Claims 4 (original): The process of claim 1 wherein the difficult-to-bond substrate is a UV varnish treated substrate or an acrylic varnish treated substrate.

Claim 5 (original): The process of claim 4 wherein the substrate to be bonded is made of paper or paperboard.

Claim 6 (original): The process of claim 1 wherein the substrate to be bonded is a grease resistance treated substrate.

Claim 7 (original): The process of claim 6 wherein the substrate to be bonded is a fluorochemical treated substrate.

Claim 8 (original): The process of claim 7 wherein the substrate is made of paper or paperboard.

Claims 9-20 (canceled)

Claim 21 (previously presented): An improved process for bonding difficult-to-bond substrates comprising bonding a first substrate to a second substrate with a hot melt adhesive composition, said composition consisting essentially of 30 to 45 % by weight ethylene n-butyl acrylate copolymer, 30 to 55 % by weight tackifier, and 20 to 40 % by weight wax, wherein the tackifier comprises at least one modified terpene tackifier.

Claim 22 (previously presented): The process of claim 21 wherein the modified terpene is a terpene phenolic.

Claims 23 (previously presented): The process of claim 21 wherein the difficult-to-bond substrate is a UV varnish treated substrate or an acrylic varnish treated substrate.

Claim 24 (previously presented): The process of claim 23 wherein the substrate to be bonded is made of paper or paperboard.

Claim 25 (previously presented): The process of claim 21 wherein the substrate to be bonded is a grease resistance treated substrate.

Claim 26 (previously presented): The process of claim 25 wherein the substrate to be bonded is a fluorochemical treated substrate.

Claim 27 (previously presented): The process of claim 26 wherein the substrate is made of paper or paperboard.

Claim 28 (previously presented): The process of claim 21 wherein said first and/or said second substrate has a surface energy of from about 35dyn/cm down to about 25dyn/cm.

Claim 29 (previously presented): The process of claim 1 wherein said first and/or said second substrate has a surface energy of from about 35dyn/cm down to about 25dyn/cm.

30 (previously presented): An improved process for bonding difficult-to-bond substrates comprising bonding a first substrate to a second substrate with a hot melt adhesive composition, said composition consisting essentially of an ethylene copolymer component, a tackifier component and wax component, wherein said ethylene copolymer comprises an ethylene n-butyl acrylate copolymer and said tackifier component comprises a modified terpene tackifier.

31 (previously presented): The process of claim 30 wherein the modified terpene is a terpene phenolic.

32 (previously presented): The process of claim 30 wherein the difficult-to-bond substrate is a UV varnish treated substrate, an acrylic varnish treated substrate or a fluorochemical treated substrate.